

ISSUE CLASSIFICATION	
Class	Subclass

PATENT NUMBER

U.S. **UTILITY** Patent Application

SCA

O.I.P.E

PATENT DATE

SCANNED

9.4

APPLICATION NO. 09/812027	CONT/PRIOR D	CLASS 257	SUBCLASS 723	ART UNIT 2811	EXAMINER <i>M. J. ...</i>
------------------------------	-----------------	--------------	-----------------	------------------	------------------------------

APPLICANTS

Bharat Shivkumar
Chuan Cheah

Conclusion

Semiconductor multichip module package with improved thermal performance; reduced size and improved moisture resistance

PTO-2040
12/88

ISSUING CLASSIFICATION

[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER <input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed. <input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____ _____ _____ <input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drawg.	Figs. Drawg.	Print Fig.	Total Claims	Print Claim for O.G.
	_____ (Assistant Examiner) _____ (Date)			NOTICE OF ALLOWANCE MAILED	
	_____ (Primary Examiner) _____ (Date)			ISSUE FEE	
				Amount Due	Date Paid
				ISSUE BATCH NUMBER	
	_____ (Legal Instruments Examiner) _____ (Date)				

WARNING:

The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.

Form **PTO-436A**
(Rev. 5/99)

FILED WITH: ☐ DISK (CRF)

FIG

☐ CD-ROM

(Attached in pocket on right inside flap)

(FACE)